

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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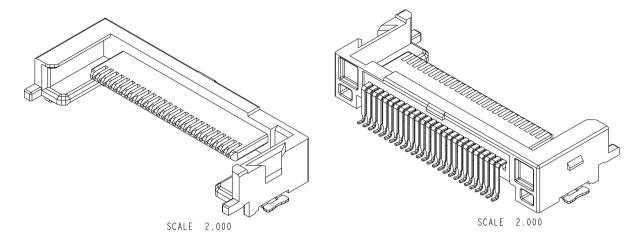
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









NOTES :

I. MATERIAL: HOUSING: HIGH TEMPERATURE THERMOPLASTIC,

UL 94 V-O FLAME RETARDANT.

TERMINAL: COPPER ALLOY.

PLATING SPEC. AS BELOW:

Ni 50u" UNDER PLATED.

Au OR GXT 30u" OVER CONTACT AREA. (ONE SIDE)

Tin 120u" OVER SOLDERING AREA.

2. PACKING SPEC. GS-14-924.

3. PRODUCT PERFORMANCE PER SPEC. GS-12-285.

4. PART NUMBER SCHEME: (EX. 10056265-222ABTMLF) 10056265-X XX X X X X X LF (LEAD FREE PLATING)

SPEC.	OPTION (CODE)									
MYLAR	WITH (M)	WITHOUT ( )								
PACKING	TRAY (S)	TAPE & REEL (T)	TUBE (P)							
HSG COLOR	BLACK (B)	NATURE (N)								
MOUNT SIDE	ABOVE (A)									
STAND-OFF	2.2 (22)									
 PLATING	GOLD (I)	GXT (2)								

5. Rohs Compatible Product Specifications

a-PLATING:

--"LF" MEANS THE PRODUCT IS LEAD-FREE, 2micro-meter MINIMUM MATTE TIN OVER

1.27micro-meter MINIMUM NICKEL UNDERPLATE.

b-MANUFACTURING PROCESS COMPATIBILITY

-THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A REFLOW SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

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	ecn no	dr	date	Eng	KENNY	TAI	05/12/05		Spec r	e f			*	A 4	1.00	0
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D	T05-0271	TAI	12/08/05	<u>•</u>		TOP	MOUNT,	2	2 5/0	)			0			Rev.
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<sup>3</sup>PDM: Rev:E

tolerance unless otherwise specified

3 PRODUCT NO. NOTE 0056265-X22AXXXLF TOOLED 0.30±0.05 ◆ 0.15 X Y Z Z 70±0. -MYLAR (OPTION) SEE NOTE 3  $38.20 \pm 0.10$ 30±0.05 2.10. 40.20±0.10 0.10 7.70±0. 3.45±0.05 1.00 25.00 27.20±0.05 X Rev TOP MOUNT, 2.2 S/O 10056265 HOST CONNECTOR ASSEMBLY catalog no CUSTOMER 10056265 sheet 2 of 3

<sup>3</sup>PDM: Rev:E

STATUS: Released 4 Printed: Jan 10, 2006

В

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3 38.20 34.20±0.05 27.70 25.00 1.00 9.80 KEEP OUT ZONE 2.50<sup>+0.20</sup>(2X) 28.70 33.50 SCALE 2.000 -ALLOWED 1.80 MM HEIGHT PARTS ONLY Rev. TOP MOUNT, 2.2 S/O 10056265 HOST CONNECTOR ASSEMBLY 10056265 CUSTOMER sheet 3 of 3 catalog no <sup>3</sup>PDM: Rev:E

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